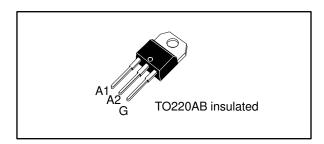


### 8 A Snubberless™ Triac

Datasheet - production data



### **Features**

- High static dV/dt
- High dynamic commutation
- 150 °C maximum T<sub>i</sub>
- Three quadrants
- Built-in ceramic for tab insulation
- Compliance to UL1557 standard (ref : E81734)
- ECOPACK®2 compliant component
- Complies with UL94,V0
- Surge capability V<sub>DSM</sub>, V<sub>RSM</sub> = 900 V

### **Benefits**

- Device is less likely to have false turn-on thanks to high dV/dt
- Better turn-off in high temperature environments thanks to (dl/dt)c
- Increase of thermal margin due to extended working T<sub>j</sub> up to 150 °C
- Better thermal resistance due to the ceramic inside the package

### **Applications**

- General purpose AC line load switching
- Motor control circuits
- Home appliances
- Heating
- Lighting
- Inrush current limiting circuits
- Overvoltage crowbar protection

### **Description**

Available in through-hole package, the T835T-8I Triac can be used for the on/off or phase angle control function in general purpose AC switching where high commutation capability is required. This device can be used without a snubber RC circuit when the limits defined are respected.

TO-220AB insulated provides tab insulation, UL1557 certified, rated at 2.5 kV RMS and UL-94, V0 resin compliance.

Package environmentally friendly ECOPACK<sup>®</sup>2 graded (RoHS and Halogen Free compliance).

Snubberless™ is a trademark of STMicroelectronics.

Figure 1: Functional diagram

A2: Anode2
A1: Anode1
G: Gate

Table 1: Device summary

Symbol	Value	Unit
I <sub>T(RMS)</sub>	8	Α
V <sub>DRM</sub> /V <sub>RRM</sub>	800	٧
V <sub>DSM</sub> /V <sub>RSM</sub>	900	V
lgт	35	mA

Characteristics T835T-8I

## 1 Characteristics

Table 2: Absolute maximum ratings (limiting values)

Symbol	Parameter			Value	Unit	
I <sub>T(RMS)</sub>	RMS on-state current (full sine wave)			8	Α	
I <sub>TSM</sub>	Non repetitive surge peak on-state current,		$t_p = 16.7 \text{ ms}$	63	A	
IISM	$T_j$ initial = 25 °C		$t_p = 20 \text{ ms}$	60	A	
l <sup>2</sup> t	I <sup>2</sup> t value for fusing, t <sub>p</sub> = 10 ms		$T_j$ initial = 25 °C	24	A <sup>2</sup> s	
dl/dt	Critical rate of rise of on-state current, $I_G = 2 \times I_{GT}$ , tr $\leq 100 \text{ ns}$	T <sub>j</sub> = 150 °C	f = 100 Hz	100	A/μs	
\/\/\/	A Repetitive peak off-state voltage		T <sub>j</sub> = 150 °C	600	V	
V <sub>DRM</sub> /V <sub>RRM</sub>			T <sub>j</sub> = 125 °C	800	V	
V <sub>DSM</sub> /V <sub>RSM</sub>	Non Repetitive peak off-state voltage		$t_p = 10 \text{ ms}$	900	V	
Ідм	Peak gate current	$t_p = 20 \ \mu s$	T <sub>j</sub> = 150 °C	4	Α	
P <sub>G(AV)</sub>	Average gate power dissipation $T_j = 150 \text{ °C}$			1	W	
T <sub>stg</sub>	Storage junction temperature range			-40 to +150	°C	
Tj	Operating junction temperature range			-40 to +150	°C	
T∟	Maximum lead temperature for soldering during 10 s			260	°C	
Vins	Insulation RMS voltage, 1 minute,	2.5	kV			

Table 3: Electrical characteristics (T<sub>j</sub> = 25 °C, unless otherwise specified)

Symbol	Test Conditions	Value	Unit		
I <sub>GT</sub> <sup>(1)</sup>	$V_D = 12 \text{ V}, \text{ R}_L = 30 \Omega$	1 - 11 - 111	Min.	1.75	mA
IGT <sup>(*)</sup>	$V_D = 12 \text{ V}, \text{ R}_L = 30 \Omega$	1 - 11 - 111	Max.	35	mA
$V_{GT}$	$V_D = 12 \text{ V}, \text{ R}_L = 30 \Omega$	1 - 11 - 111	Max.	1.3	V
V <sub>GD</sub>	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega, T_j = 150 \text{ °C}$	1 - 11 - 111	Min.	0.2	V
IL	lg = 1.2 x lgr	I - III	Max.	60	mA
	IG = 1.2 X IGT	II	Max.	70	mA
Ін	I <sub>T</sub> = 500 mA, gate open		Max.	40	mA
dV/dt	V <sub>D</sub> = 536 V, gate open	T <sub>j</sub> = 125 °C	Min.	2000	V/µs
u v/ut	V <sub>D</sub> = 402 V, gate open	T <sub>j</sub> = 150 °C	IVIII I.	1000	V/µs
(dl/dt)c	Without apulbor (d)/(dt)a . 20 )/(up	T <sub>j</sub> = 125 °C	Min.	8	A/ms
	Without snubber, (dV/dt)c > 20 V/μs	T <sub>j</sub> = 150 °C		4	A/ms

#### Notes:

 $<sup>^{(1)}</sup>$ For both polarities of A2 referenced to A1.

T835T-8I Characteristics

**Table 4: Static characteristics** 

Symbol	Test conditions	Tj		Value	Unit	
V <sub>TM</sub> <sup>(1)</sup>	$I_T = 11.3 \text{ A}, t_p = 380 \ \mu s$	25 °C	Max.	1.60	٧	
V <sub>TO</sub>	Threshold on-state voltage	150 °C	Max.	0.87	٧	
R <sub>D</sub>	Dynamic resistance	150 °C	Max.	80	mΩ	
	V V 900 V	V <sub>DRM</sub> = V <sub>RRM</sub> = 800 V	25 °C	Max.	5	μΑ
I <sub>DRM</sub> /I <sub>RRM</sub>	VDRM = VRRM = 800 V	125°C	iviax.	1.0	mA	
	$V_{DRM} = V_{RRM} = 600 \text{ V}$	150 °C	Max.	2.5	mA	

### Notes:

**Table 5: Thermal resistance** 

Symbol	Parameter Value			
R <sub>th(j-c)</sub>	Junction to case (AC)	Max.	2.8	0 <b>0</b> /M
R <sub>th(j-a)</sub>	Junction to ambient	60	°C/W	

 $<sup>^{(1)}</sup>$ For both polarities of A2 referenced to A1.

Characteristics T835T-8I

# 1.1 Characteristics (curves)

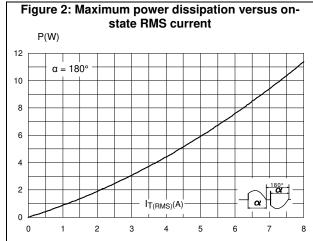


Figure 3: On-state RMS current versus case temperature

I<sub>T(RMS)</sub>(A)

10

9

8

7

6

5

4

3

2

1

0

0

25

50

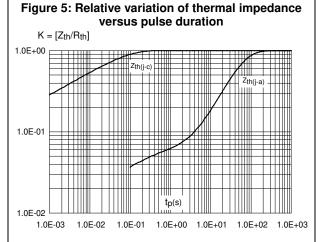
75

100

125

150

Figure 4: On-state RMS current versus ambient temperature (free air convection)  $I_{T(RMS)}(A)$ 3.0  $\alpha = 180^{\circ}$ 2.5 2.0 1.5 1.0 0.5 Ta(°C) 0.0 25 50 75 150



T835T-8I Characteristics

Figure 6: Relative variation of gate trigger voltage and current versus junction temperature (typical values)

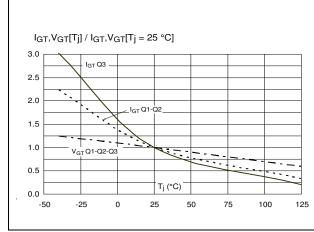


Figure 7: Relative variation of holding current and latching current versus junction temperature (typical values)

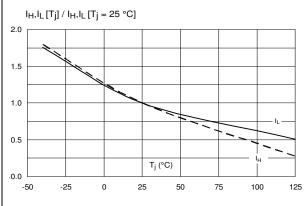


Figure 8: Surge peak on-state current versus number of cycles

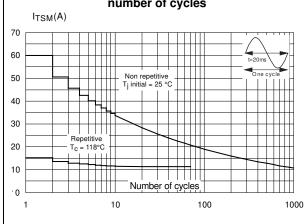


Figure 9: Non repetitive surge peak on-state current for a sinusoidal pulse with width tp < 10 ms

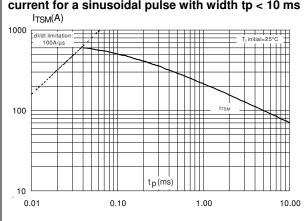


Figure 10: On-state characteristics (maximum values)

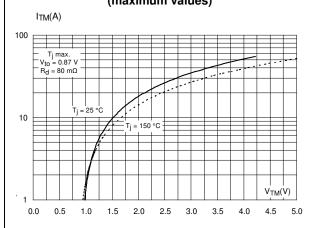
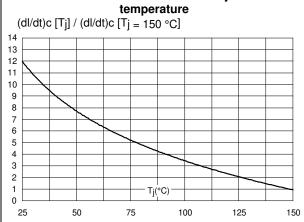
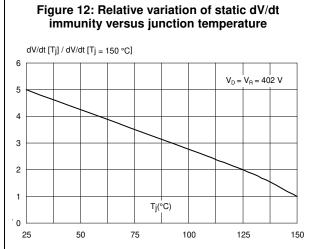
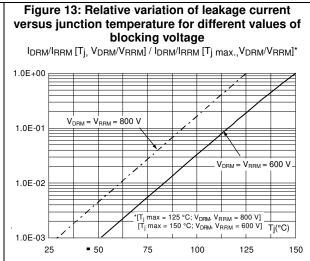


Figure 11: Relative variation of critical rate of decrease of main current versus junction



Characteristics T835T-8I





T835T-8I Package information

## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- ECOPACK®2 (Lead-free plating and Halogen free package compliance)
- Lead-free package leads finishing
- Halogen-free molding compound resin meets UL94 standard level V0.
- Recommended torque (for through-hole package): 0.4 to 0.6 N·m

## 2.1 TO-220AB Insulated package information

Figure 14: TO-220AB Insulated package outline  $\overline{\mathsf{c}}$ В **b2** Resin gate 0.5 mm max. protusion(1) F Α 14 13 **c2** a1 12 a2 М с1 Resin gate 0.5 mm **b1** max. protusion(1) (1)Resin gate position accepted in one of the two positions or in the symmetrical opposites.

Table 6: TO-220AB Insulated package mechanical data

	Dimensions					
Ref.		Millimeters			Inches <sup>(1)</sup>	
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	15.20		15.90	0.5984		0.6260
a1		3.75			0.1476	
a2	13.00		14.00	0.5118		0.5512
В	10.00		10.40	0.3937		0.4094
b1	0.61		0.88	0.0240		0.0346
b2	1.23		1.32	0.0484		0.0520
С	4.40		4.60	0.1732		0.1811
c1	0.49		0.70	0.0193		0.0276
c2	2.40		2.72	0.0945		0.1071
е	2.40		2.70	0.0945		0.1063
F	6.20		6.60	0.2441		0.2598
I	3.73		3.88	0.1469		0.1528
L	2.65		2.95	0.1043		0.1161
12	1.14		1.70	0.0449		0.0669
13	1.14		1.70	0.0449		0.0669
14	15.80	16.40	16.80	0.6220	0.6457	0.6614
М		2.6			0.1024	

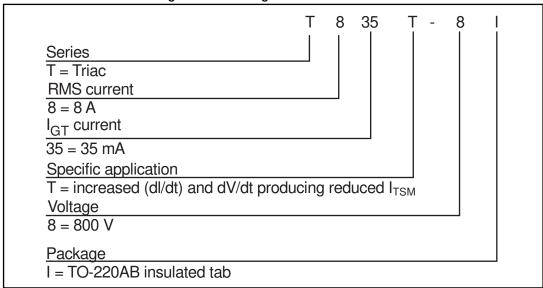
### Notes:

 $<sup>^{(1)}</sup>$ Inch dimensions are for reference only.

T835T-8I Ordering information

# 3 Ordering information

Figure 15: Ordering information scheme



**Table 7: Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
T835T-8I	T835T-8I	TO-220AB insulated	2.3 g	50	Tube

## 4 Revision history

**Table 8: Document revision history** 

Date	Revision	Changes	
17-Oct-2017	1	Initial release.	
06-Nov-2017	2	Updated Table 4: "Static characteristics".	

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